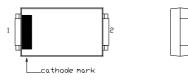
Nihon Inter Electronics Corporation

$\textbf{SBD} \qquad \texttt{Type} : NSQ03A06$

FEATURES

- * FLAT-PAK Surface Mounting Device
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * 30 Volts through 60Volts Types Available
- * Packaged in 16mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING







Maximum Ratings

Approx Net Weight:0.16g

Rating	Symbol	NSQ03A06			Unit
Repetitive Peak Reverse Voltage	V _{RRM}	60			V
Average Rectified Output Current	I_{o}	1.36	Ta=25°C *1	50Hz Half Sine	Α
		3.0	Tl=96°C	Wave Resistive Load	A
RMS Forward Current	I _F (RMS)	4.71			A
Surge Forward Current	I _{FSM}	50	50Hz Half Sine Wav	A	
		30	Non-repetitive		
Operating JunctionTemperature Range	T_{jw}	-40 to +150			°C
Storage Temperature Range	Tstg	-40 to +150			°C

Electrical • Thermal Characteristics

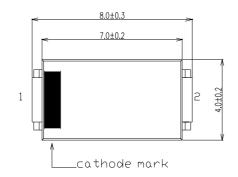
Ch	aracteristics	Symbol	nbol Conditions		Тур.	Max.	Unit
Peak Reve	erse Current	I_{RM}	Tj= 25°C, V _{RM} = V _{RRM}	-	-	3	mA
Peak Forw	vard Voltage	V_{FM}	Tj= 25°C, I _{FM} = 3.0A	-	-	0.58	V
Thermal	Junction to Ambient	Rth _(j-a)	Alumina Substrate Mounted *1	-	-	89	°C/W
Resistance	Junction to Lead	Rth _(j-l)	+	-	-	13	C/VV

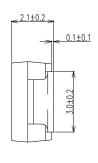
^{*1} Alumina Substrate Mounted (Soldering Lands=2x3.5mm,Both Sides)

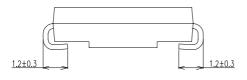
(Tl: Lead Temperature)

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NSQ03A06 OUTLINE DRAWING (Dimensions in mm)









SOLDERING PAD

